

Listing of Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-20. (Cancelled)

21. (Original) A method for rapidly heating semiconductor wafers in a thermal processing chamber, said method comprising the steps of:

placing a semiconductor wafer in a thermal processing chamber;

rapidly heating said semiconductor wafer to a predetermined maximum temperature using light energy; and

rapidly cooling said semiconductor wafer through the use of an active cooling device, said cooling device comprising a cooling member maintained at a temperature lower than the wafer.